

LP-NSM150

Surface mount fuses

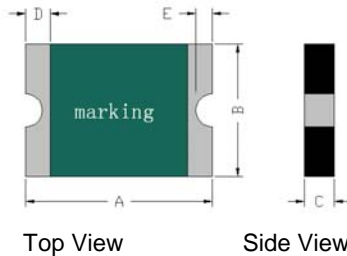
Features

- Small size of 1206
- Lead-free and compliant with the European Union RoHS Directive 2002/95/EC
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA



Product Dimensions (mm)

Part number	A	B	C	D	E	Part marking
	Max.	Max.	Max.	Min.	Min.	
LP-NSM150	3.50	1.80	1.80	0.10	0.20	N

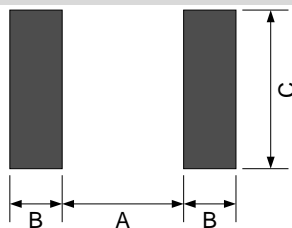


Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}	$P_{d\ typ}$	R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A) Time(S)	(W)	(Ω)	(Ω)
LP-NSM150	1.50	3.00	6	40	8.0 1.00	0.6	0.04	0.12

I_H =Hold current: maximum current at which the device will not trip at 25°C still air.
 I_T =Trip current: minimum current at which the device will always trip at 25°C still air.
 V_{max} =Maximum voltage device can withstand without damage at rated current.
 I_{max} =Maximum fault current device can withstand without damage at rated voltage.
 T_{trip} =Maximum time to trip(s) at assigned current.
 $P_{d\ typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min} =Minimum device resistance at 25°C prior to tripping.
 R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-NSM150	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase, hot air oven.
 * Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

Package Information

Tape & Reel: 4000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

